MTTL/SECT/28/2025-26 **Date: August 26, 2026**

The Secretary, Listing Department, **BSE Ltd.,** Phiroze Jeejeebhoy Towers, Dalal Street, Fort, Mumbai-400001. **Scrip Code: 526263**	The Manager, Listing Department, **National Stock Exchange of India Limited,** Exchange Plaza, 5th Floor, Plot No. C/1, G Block, Bandra Kurla Complex, Bandra (E), Mumbai-400051. **Symbol: MOLDTECH - EQ**

Sir/Madam,

Sub: Press Release on Issuance of Bonus Equity Shares

We enclose herewith a copy of the Press Release issued by Mold-Tek Technologies Limited ("Company") on Issuance of Bonus Equity Shares.

A copy of this intimation is also being made available on the website of the Company at www.moldtekengineering.com

This is for your kind information and record.

Thanking you,

For Mold-Tek Technologies Limited

PRATEEK KUMAR TIWARI
Digitally signed by PRATEEK KUMAR TIWARI
Date: 2026.08.26 15:20:30 +05'30'

Prateek Kumar Tiwari
Company Secretary & Compliance Officer

Encl: A/a

Issuance of Bonus Shares by Mold-Tek Technologies Limited

As the Company proudly celebrates its 25th anniversary, the Board of Directors of Mold-Tek Technologies Limited ("Company"), at its meeting held today, is pleased to announce that it has considered and approved the proposal for issuance of bonus equity shares in the proportion of 1:1, i.e., one bonus equity share for every one existing fully paid-up equity share held by the eligible shareholders as on the record date, which will be announced subsequently. This proposed issuance is a gesture of appreciation and gratitude to the members for their continued trust, confidence and support, which have been integral to the Company's journey and growth over the years. The issuance of bonus equity shares shall be subject to the approval of the shareholders at the Annual General Meeting of the Company scheduled to be held on September 21, 2026, and such other statutory and regulatory approvals as may be applicable.

The existing authorised equity share capital of the Company stands at ₹13,00,00,000, while the existing paid-up equity share capital is ₹5,76,10,236**.** Pursuant to the proposed issuance of bonus equity shares in the ratio of 1:1, the paid-up equity share capital of the Company will increase to ₹11,52,20,472**.**

The Reserves & Surplus (in India) of the Company stood at ₹ 1,15,00,36,940 as at March 31, 2026**.**

Further it is clarified that the proposal of issue of bonus shares shall not impact the solvency margin and any other financial parameters of the Company.

Speaking on the occasion, Mr. Laxmana Rao Janumahanti, Chairman & Managing Director of the Company, said:

"As we proudly commemorate the 25th anniversary of Mold-Tek Technologies Limited, I am pleased to share that the Board has proposed the issuance of bonus equity shares in the ratio of 1:1, subject to the approval of the shareholders and such other applicable statutory and regulatory approvals. This significant milestone marks an important chapter in the Company's journey and provides an opportunity to express our sincere appreciation for the continued trust and confidence reposed in us by our valued shareholders. As we look ahead to the next phase of our journey, we remain committed to building on our strong foundation, pursuing sustainable growth and creating lasting value for all our stakeholders".

Mold-Tek Technologies Limited
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